

advanced

45 V 15 A

0.63 V

# **Schottky**

High Performance Schottky Diode Low Loss and Soft Recovery Single Diode

Part number (Marking on product)

**DSA 15 IM 45IB** 

## Features / Advantages:

- Very low Vf
- Extremely low switching losses
- Low Irm-values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- · Low noise switching
- Low losses

## **Applications:**

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

### Package:

 $V_{RRM} =$ 

TO-262 (I2Pak)

- Industry standard outline
- Epoxy meets UL 94V-0RoHS compliant

### Ratings

Symbol	Definition	Conditions		min.	typ.	max.	Unit
V <sub>RRM</sub>	max. repetitive reverse voltage		$T_{VJ} = 25 ^{\circ}C$			45	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 45 V	T <sub>VJ</sub> = 25 °C			0.3	mA
		$V_R = 45 V$	$T_{VJ}$ = 125 °C			2.5	mA
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 15 A	T <sub>vJ</sub> = 25 °C			0.75	V
		$I_F = 30 A$				0.91	V
		I <sub>F</sub> = 15 A	T - 125°C			0.63	V
		$I_F = 30 A$	$T_{VJ} = 125$ °C			0.79	V
I <sub>FAV</sub>	average forward current	rectangular, d = 0.5	$T_c = 155 ^{\circ}C$			15	Α
V <sub>F0</sub>	threshold voltage slope resistance $T_{VJ} = 175^{\circ}$		T <sub>vJ</sub> = 175 °C			0.42	V
						9.9	mΩ
$R_{thJC}$	thermal resistance junction to case					1.75	K/W
$T_{vJ}$	virtual junction temperature			-55		175	°C
P <sub>tot</sub>	total power dissipation		$T_c = 25 ^{\circ}C$			85	W
I <sub>FSM</sub>	max. forward surge current	$t_p = 10 \text{ ms } (50 \text{ Hz}), \text{ sine}$	$T_{VJ} = 45 ^{\circ}\text{C}$			140	Α
CJ	junction capacitance	$V_R = V$ ; f = 1 MHz	$T_{VJ} = 25 ^{\circ}C$				pF
E <sub>AS</sub>	non-repetitive avalanche energy	$I_{AS} = A; L = 100 \mu H$	$T_{VJ} = 25 ^{\circ}C$			tbd	mJ
I <sub>AR</sub>	repetitive avalanche current	$V_A = 1.5 \cdot V_R \text{ typ.; } f = 10 \text{ kHz}$	<u>:</u>			tbd	Α

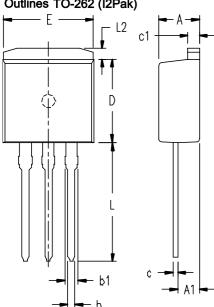


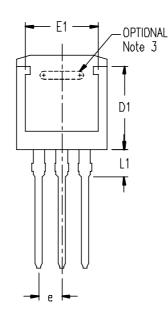
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				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
I <sub>RMS</sub>	RMS current	per pin*			35	Α	
R <sub>thCH</sub>	thermal resistance case to heatsink			0.50		K/W	
$M_{\scriptscriptstyle D}$	mounting torque					Nm	
F <sub>c</sub>	mounting force with clip		20		60	N	
T <sub>stg</sub>	storage temperature		-55		150	°C	
Weight				2		g	

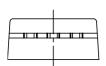
<sup>\*</sup> Irms is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip. In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

### Outlines TO-262 (I2Pak)





MYZ	INCHES		MILLIMETERS		
2114	MIN	MAX	MIN	MAX	
Α	.160	.190	4.06	4.83	
A1	.080	.110	2.03	2.79	
b	.025	.035	0.64	0.88	
b1	.025	.039	1.14	1.40	
С	.018	.025	0.46	0.64	
с1	.045	.055	1.14	1.40	
D	.340	.380	8.64	9.65	
D1	.270	.290	6.86	7.37	
E	.380	.405	9,65	10.29	
E1	.245	.320	6,22	8.13	
е	.100	BSC	2.54 BSC		
L	.500	.560	12.70	14.22	
L1	.100	.125	2.54	3.18	
L2	.040	.055	1.02	1.40	



- 1. This drawing will meet all dimensions requirement of JEDEC outline T0-262 AA.
- 2. All metal surface are matte pure tin plated except trimmed area.
- 3. Inter locking slot depends upon frame type.